



STPR1620CG

ULTRA FAST RECOVERY RECTIFIER DIODES

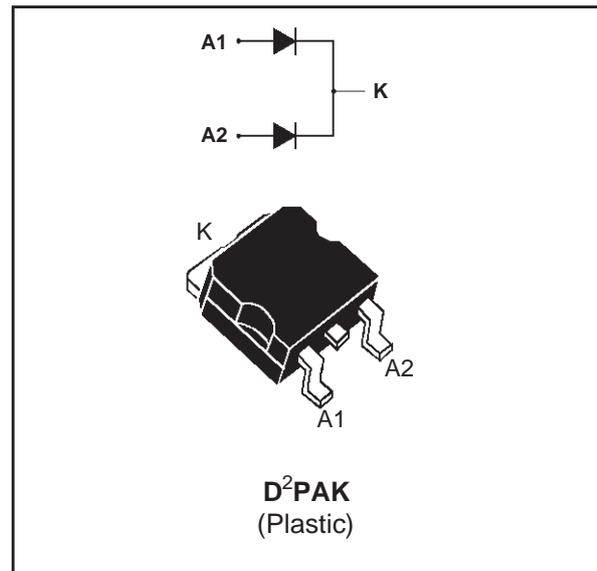
FEATURES

- SUITED FOR SMPS
- LOW LOSSES
- LOW FORWARD AND REVERSE RECOVERY TIME
- HIGH SURGE CURRENT CAPABILITY
- HIGH AVALANCHE ENERGY CAPABILITY
- SMD PACKAGE

DESCRIPTION

Low cost dual center tap rectifier suited for switchmode power supply and high frequency DC to DC converters.

Packaged in D²PAK this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



ABSOLUTE MAXIMUM (limiting values)

| Symbol | Parameter | | Value | Unit |
|--------------------|---|--|----------------------|--------------------------------------|
| V_{RRM} | Repetitive peak reverse voltage | | 200 | V |
| $I_{F(RMS)}$ | RMS forward current | Per diode | 20 | A |
| $I_{F(AV)}$ | Average forward current $\delta = 0.5$ | $T_c = 120^\circ\text{C}$ Per diode Per device | 8 16 | A |
| I_{FSM} | Surge non repetitive forward current | $t_p = 10\text{ms}$ sinusoidal Per diode | 80 | A |
| T_{stg} T_j | Storage temperature range Maximum junction temperature | | - 65 to + 150 150 | $^\circ\text{C}$ $^\circ\text{C}$ |

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THERMAL RESISTANCES

| Symbol | Parameter | Value | Unit |
|---------------|------------------|-----------|----------------------|
| $R_{th(j-c)}$ | Junction to case | Per diode | 3.0 |
| | | Total | |
| $R_{th(c)}$ | Coupling | | $^{\circ}\text{C/W}$ |

When the diodes 1 and 2 are used simultaneously :
 $\Delta T_j(\text{diode } 1) = P(\text{diode } 1) \times R_{th(j-c)} (\text{Per diode}) + P(\text{diode } 2) \times R_{th(c)}$

STATIC ELECTRICAL CHARACTERISTICS

| Symbol | Test Conditions | | Min. | Typ. | Max. | Unit |
|------------|-----------------------------|----------------------|------|------|------|---------------|
| I_R^* | $T_j = 25^{\circ}\text{C}$ | $V_R = V_{RRM}$ | | | 50 | μA |
| | $T_j = 100^{\circ}\text{C}$ | | | | 0.6 | mA |
| V_F^{**} | $T_j = 125^{\circ}\text{C}$ | $I_F = 8 \text{ A}$ | | | 0.99 | V |
| | $T_j = 125^{\circ}\text{C}$ | $I_F = 16 \text{ A}$ | | | 1.20 | |
| | $T_j = 25^{\circ}\text{C}$ | $I_F = 16 \text{ A}$ | | | 1.25 | |

Pulse test : * $t_p = 5 \text{ ms}$, duty cycle < 2 %
** $t_p = 380 \mu\text{s}$, duty cycle < 2 %

RECOVERY CHARACTERISTICS

| Symbol | Test Conditions | | Min. | Typ. | Max. | Unit |
|----------|----------------------------|--|------|------|------|------|
| trr | $T_j = 25^{\circ}\text{C}$ | $I_F = 0.5\text{A}$ $I_{rr} = 0.25\text{A}$ $I_R = 1\text{A}$ | | | 30 | ns |
| tfr | $T_j = 25^{\circ}\text{C}$ | $I_F = 1\text{A}$ $t_r = 10 \text{ ns}$ $V_{FR} = 1.1 \times V_F$ | | 20 | | ns |
| V_{FP} | $T_j = 25^{\circ}\text{C}$ | $I_F = 1\text{A}$ $t_r = 10 \text{ ns}$ | | 3 | | V |

To evaluate the conduction losses use the following equation :
 $P = 0.78 \times I_{F(AV)} + 0.026 \times I_{F(RMS)}^2$

Fig.1 : Average forward power dissipation versus average forward current (Per diode).

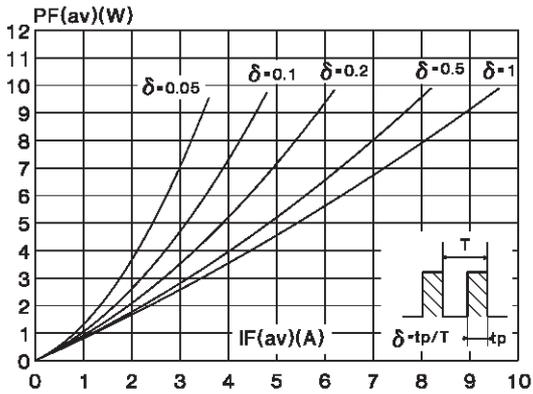


Fig.2 : Peak current versus form factor. (Per diode)

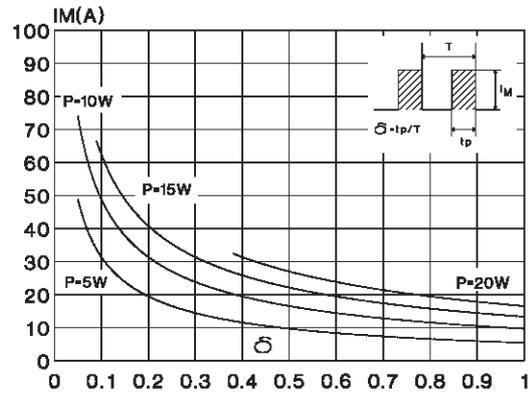


Fig.3 : Average current versus ambient temperature. (duty cycle : 0.5) (Per diode)

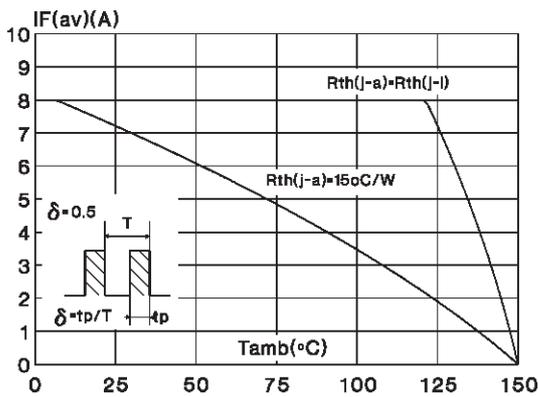


Fig.4 : Non repetitive surge peak forward current versus overload duration (Maximum values) (Per diode).

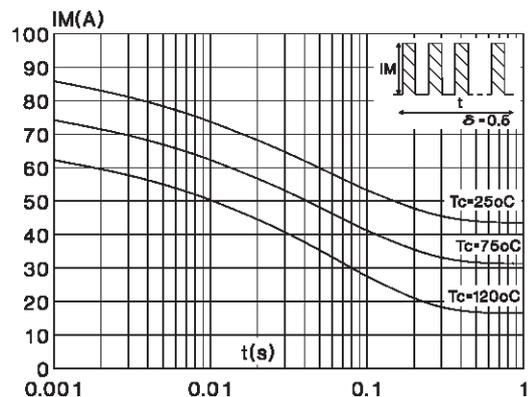


Fig.5 : Relative variation of thermal transient impedance junction to case versus pulse duration (Per diode).

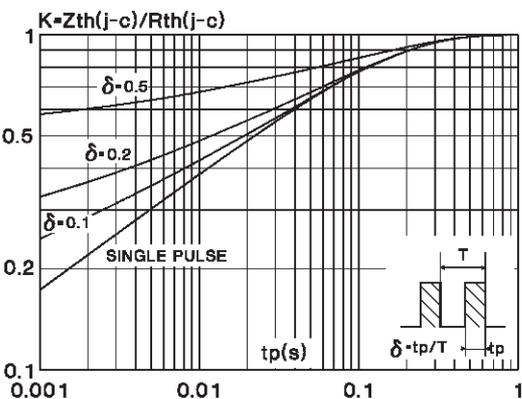
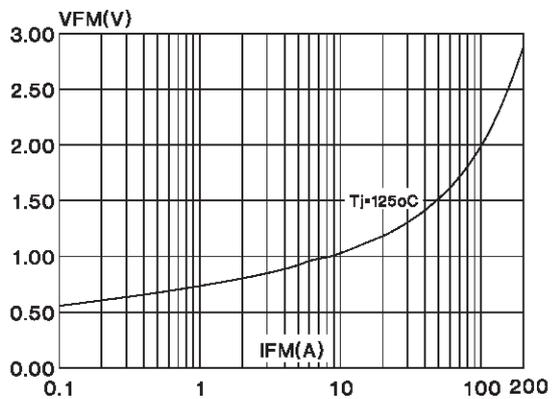


Fig.6 : Forward voltage drop versus forward current. (maximum values) (Per diode).



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Fig.7 : Junction capacitance versus reverse voltage applied (Typical values) (Per diode).

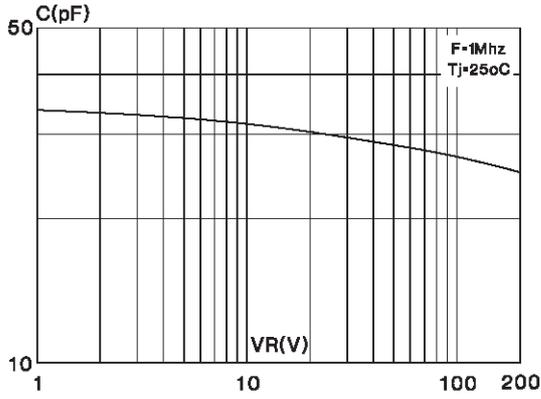


Fig.8 : Recovery charges versus dI_F/dt (Per diode).

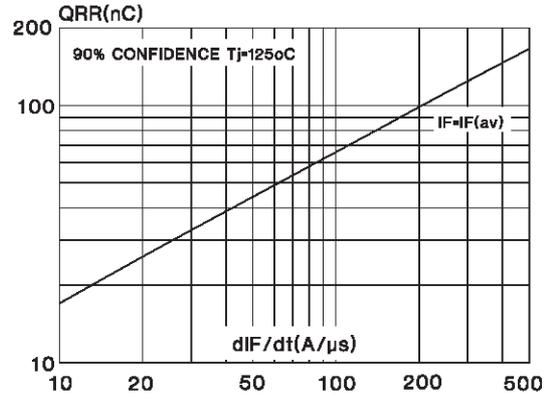


Fig.9 : Peak reverse current versus dI_F/dt (Per diode).

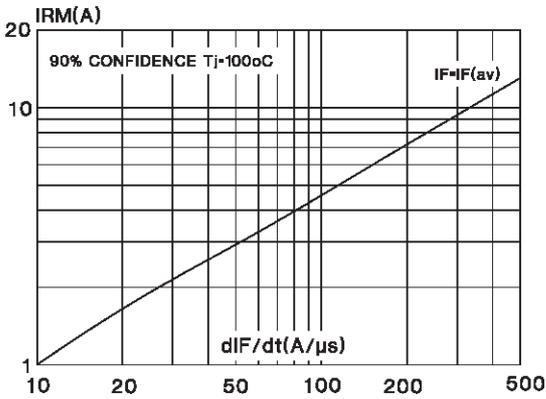
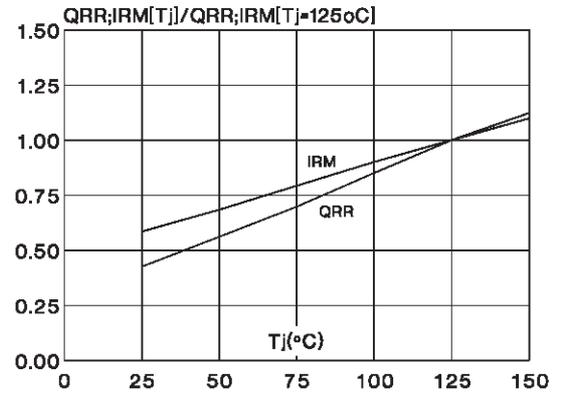
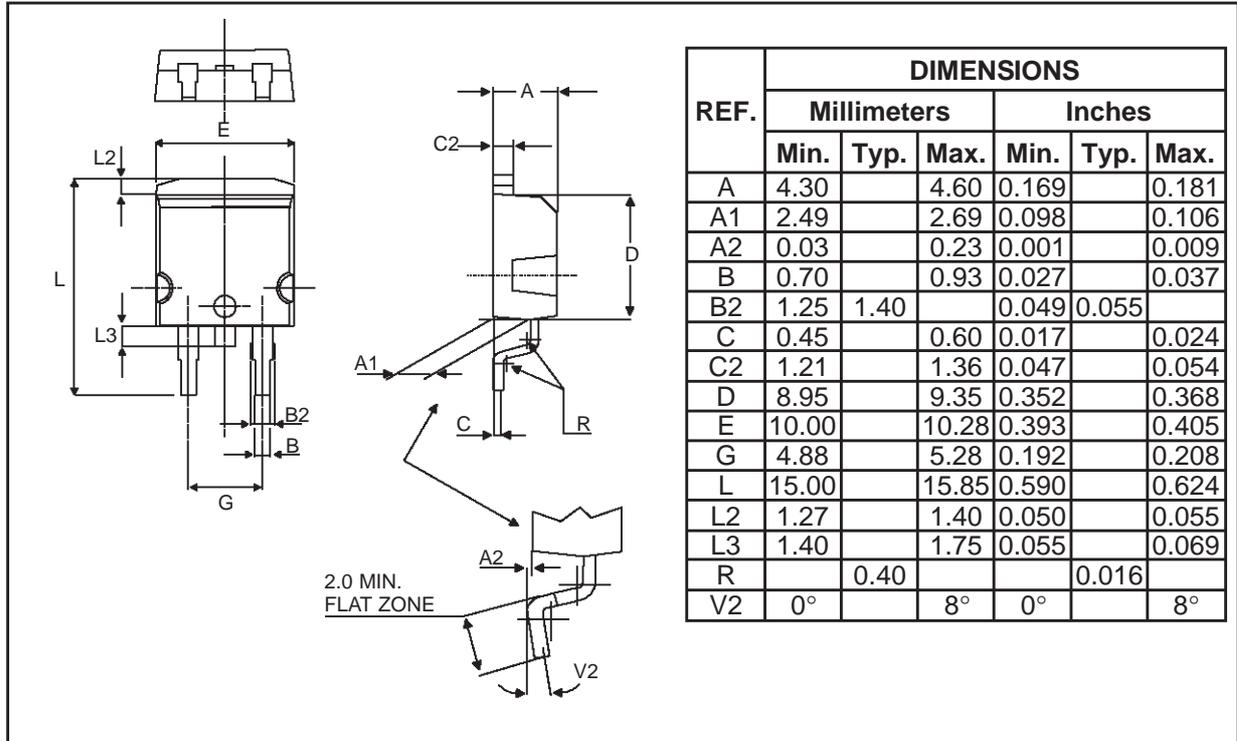


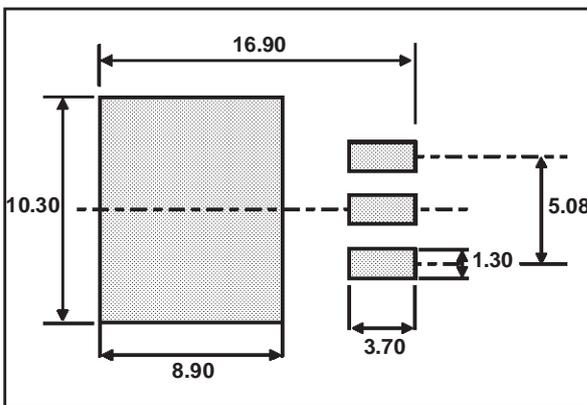
Fig.10 : Dynamic parameters versus junction temperature (Per diode).



PACKAGE MECHANICAL DATA
D²PAK (Plastic)



FOOT PRINT (in millimeters)



- **Marking** : Type number
- **Cooling method** : C
- **Weight** : 1.8 g

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